Combined SDF and MFI Conference

Call for Papers

Combined SDF and MFI

This year the combined IEEE 2023 Symposium Sensor Data Fusion and International Conference on Multisensor Fusion and Integration (SDF-MFI) will take place in Bonn, Germany. We are happy to announce the collaboration of two great conferences on robotics, data fusion, automation and intelligent systems in combined one-track conference. The Uniclub Bonn next to the Rhine river at the center of the former capital provides a great venue.

Topics

Theory: Probability theory, Bayesian inference, nonlinear estimation, Dempster-Shafer, fuzzy sets, logic, machine learning, neural networks, distributed architectures.

Sensors: RGB cameras, depth cameras, radar and sonar devices, laser scanner, infrared sensors, IMU, gyroscopes.

Algorithms for: tracking and localization, recognition, perception, AI in robotics, cognitive systems, sensor registration, big data, sensor management, distributed sensor systems, SLAM, visual servoing, learning by demonstration.


Fees

€ 299.-  Students
€ 499.-  Regular

- For the student registration a proof of the student status is required.
- One registration covers one paper only.

Contributions

Prospective authors are encouraged to submit high-quality full draft papers (6-8 pages, IEEE format). All submissions are subject to a peer-review process by the technical program committee. Accepted and presented papers will be submitted to IEEE for publication. At least one of the authors of each accepted contribution is expected to register for the conference and to present the paper. For details contact www.fkie.fraunhofer.de/sdf2023.

Important Dates

31.08.2023  Submission of full draft papers
13.10.2023  Notification of acceptance
03.11.2023  Submission of the final version
27.11.2023  Start of the conference

Organisation

Executive Chairs:
- Wolfgang Koch, Fraunhofer FKIE and University of Bonn, w.koch@ieee.org
- Uwe D. Hanebeck, Karlsruhe Institute of Technology KIT, uwe.hanebeck@kit.edu

Technical Program Chairs:
- Florian Pfaff, Karlsruhe Institute of Technology KIT
- Felix Govaers, Fraunhofer FKIE, Germany

Technical Program Committee

Marcus BAUM, University of Göttingen, GER; Jürgen BESTLE, HENSOLDT, GER; Christian BRANDLHUBER, 21strategies, GER; Chee CHONG, Consultant, CA, USA; Stefano CORALUPPI, STO, MA, USA; Armin B. CREMERS, University of Bonn, GER; Daniel CREMERS, Technical University Munich, GER; Klaus DIETMAYER, University of Ulm, GER; Darin DUNHAM, Lockheed Martin, USA; Bhargav DURASAMY, Daimler, GER; Murat EFE, Antkara University, TK; Frank EHLERS, FWG, GER; Dietrich FRÄNKEN, Hensoldt; GER; Jesus GARCIÀ, University Carlos III, Madrid, ES; Fredrik GUSTAFSSON, Linköping University, SW; Uwe D. HANEBECK, Karlsruhe Institute of Technology KIT, GER; Bernhard KRACH, Airbus, GER; Joerg KUSHAUER, Diehl BGT Defence, GER; Henry LEUNG, University of California, CA; Lyudmila MIHAYLOVA, University of Sheffield, UK; Gee Wah NG, DSO, SGP; Umut ORGUNER, University of Ankara, TR; Johannes REUTER, University of Applied Sciences Konstanz, GER; Stefan REUTER, Robert Bosch GmbH, GER; Lauro SINDARIO, University of Udine, IT; Klaus-Dieter SOMMER, University of Ilmenau, GER; Roy L. STREIT, Metron Inc., USA; Jorn THIELECKE, Universität Erlangen, GER; Reiner THOMA, Technical University Ilmenau, GER; Martin ULMKE, Fraunhofer FKIE, GER;